

Lonten N-channel 600V, 7A Power MOSFET

Description

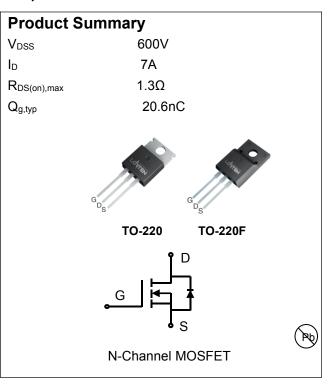
The Power MOSFET is fabricated using the advanced planar VDMOS technology. The resulting device has low conduction resistance, superior switching performance and high avalance energy.

Features

- ♦ Low R_{DS(on)}
- ◆ Low gate charge (typ. Q_g =20.6nC)
- ◆ 100% UIS tested
- RoHS compliant

Applications

- Power faction correction.
- Switched mode power supplies.
- ◆ LED driver.



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	600	V
Continuous drain current (T _C = 25°C)	I _D	7	А
(T _C = 100°C)		4.2	A
Pulsed drain current 1)	I _{DM}	28	A
Gate-Source voltage	V _{GSS}	±30	V
Avalanche energy, single pulse 2)	E _{AS}	405	mJ
Peak diode recovery dv/dt 3)	dv/dt	5	V/ns
Power Dissipation TO-220F (T _C = 25°C)		39	W
Derate above 25°C		0.31	W/°C
Power Dissipation	P _D		
TO-220\ TO-251\ TO-252 ($T_C = 25^{\circ}C$)		100	W
Derate above 25°C		0.8	W/°C
Operating juncition and storage temperature range	T _J , T _{STG}	-55 to +150	°C
Continuous diode forward current	Is	7	Α
Diode pulse current	I _{S,pulse}	28	A

Thermal Characteristics

Parameter	Symbol	Value		l lait	
Farameter	Symbol	TO-220F	TO-220\ TO-251\ TO-252	Unit	
Thermal resistance, Junction-to-case	R _{eJC}	3.2	1.25	°C/W	
Thermal resistance, Junction-to-ambient	R _{0JA}	62.5	110	°C/W	

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Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube	Units/Real
LNC7N60	TO-220	LNC7N60	50	
LND7N60	TO-220F	LND7N60	50	

Electrical Characteristics T_c = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250 uA	600	-	-	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250 uA	2	-	4	V
Drain cut-off current	I _{DSS}	V _{DS} =600 V, V _{GS} =0 V,				
		T _j = 25°C	-	-	1	μΑ
		T _j = 125°C	-		100	
Gate leakage current, Forward	I _{GSSF}	V _{GS} =30 V, V _{DS} =0 V	-	-	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-30 V, V _{DS} =0 V	-	-	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =3.5 A	-	1.0	1.3	Ω
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V,	-	1112	-	
Output capacitance	Coss	f = 1 MHz	-	90	-	pF
Reverse transfer capacitance	C _{rss}		-	5	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 300 V, I _D = 7 A	-	12	-	
Rise time	tr	R _G = 10 Ω, V _{GS} =15 V	-	30	-	ns
Turn-off delay time	t _{d(off)}		-	52	-	
Fall time	t _f		-	12	-	
Gate charge characteristics	•		1	-		
Gate to source charge	Q _{gs}	V _{DD} =480 V, I _D =7 A,	-	5.4	-	
Gate to drain charge	Q _{gd}	V _{GS} =0 to 10 V	-	7.4	-	nC
Gate charge total	Qg		-	20.6	-	1
Gate plateau voltage	V _{plateau}	1	-	5.1	-	V
Reverse diode characteristics	.			•		
Diode forward voltage	V _{SD}	V _{GS} =0 V, I _F =7 A	-	-	1.5	V
Reverse recovery time	t _{rr}	V _R =300 V, I _F =7 A,	-	306	-	ns
Reverse recovery charge	Qrr	dI _F /dt=100 A/µs	-	2.1	-	μC
Peak reverse recovery current	I _{rrm}	1	-	13.7	-	Α

Notes:

- 1. Pulse width limited by maximum junction temperature.
- 2. L=10mH, I_{AS} = 9A, V_{DD} =60V, Starting T_j = 25°C.
- 3. I_{SD} = 7A, di/dt \leq 100A/us, $V_{DD}\leq$ B V_{DS} , Starting T_j = 25°C.

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Electrical Characteristics Diagrams

Figure 1. Typical Output Characteristics

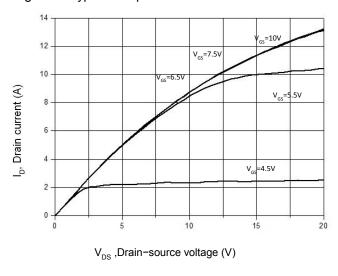


Figure 3. On-Resistance Variation vs. Drain Current

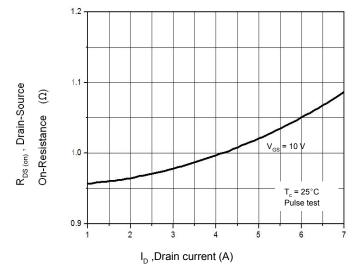


Figure 5. Breakdown Voltage vs. Temperature

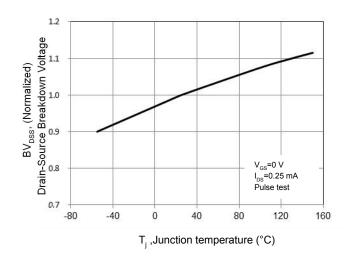


Figure 2. Transfer Characteristics

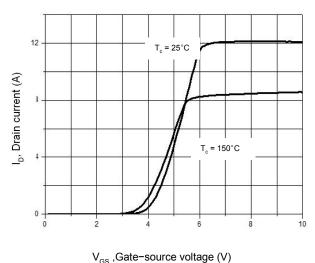


Figure 4. Threshold Voltage vs. Temperature

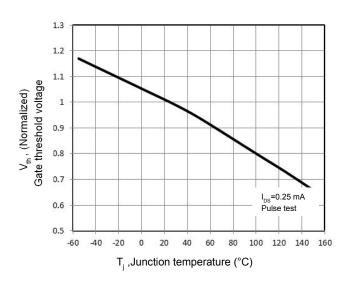


Figure 6. On-Resistance vs. Temperature

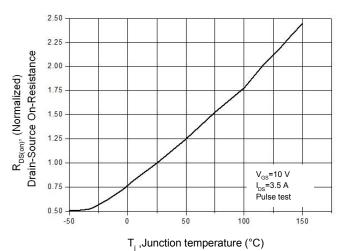




Figure 7. Capacitance Characteristics

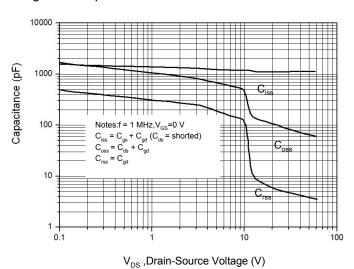


Figure 9. Maximum Safe Operating Area TO-220F

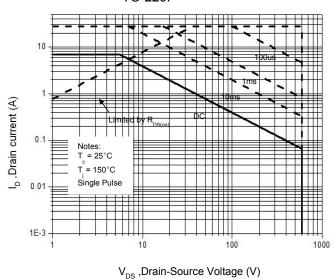


Figure 11. Power Dissipation vs. Temperature TO-220F

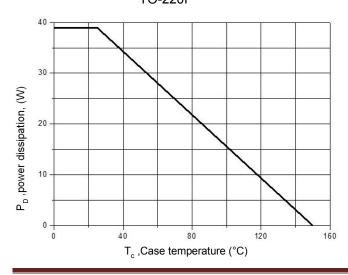


Figure 8. Gate Charge Characterist

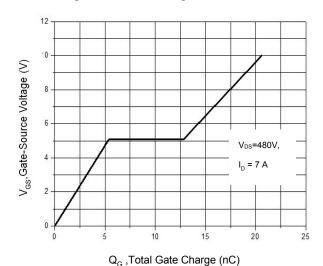


Figure 10. Maximum Safe Operating Area TO-220/ TO-251/TO-252

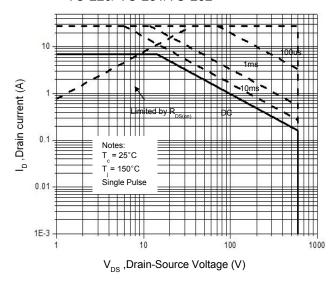


Figure 12. Power Dissipation vs. Temperature TO-220/ TO-251/TO-252

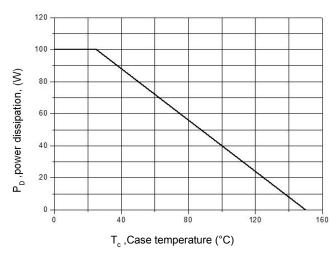




Figure 13. Continuous Drain Current vs. Temperature

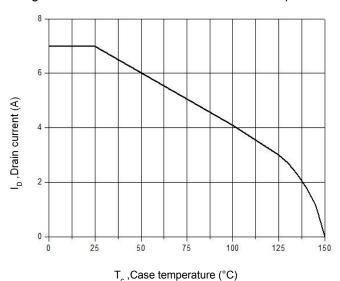


Figure 14. Body Diode Transfer Characteristics

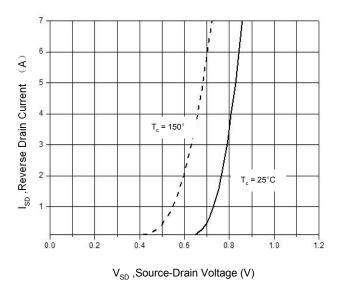


Figure 15 Transient Thermal Impendance, Junction to Case, TO-220F

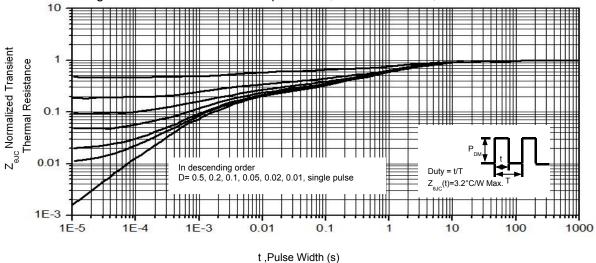
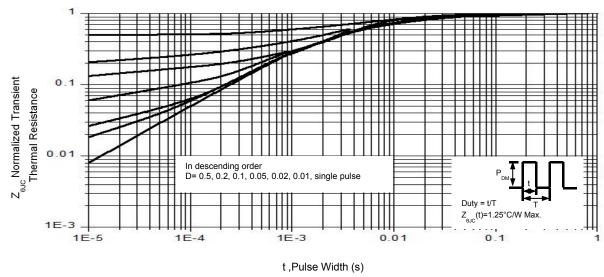


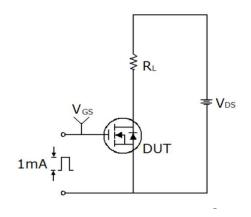
Figure 16. Transient Thermal Impendance, Junction to Case, TO-220/TO-251/TO-252

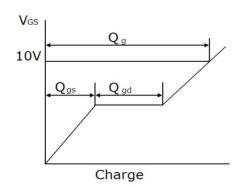


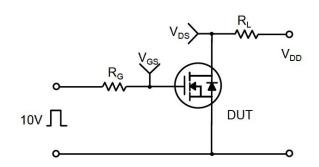
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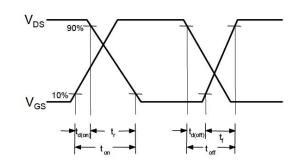


Gate Charge Test Circuit & Waveform

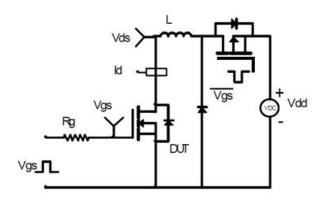


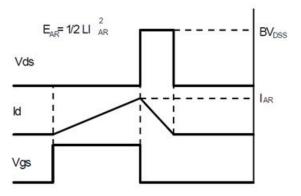






Unclamped Inductive Switching Test Circuit & Waveforms

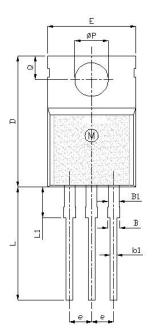


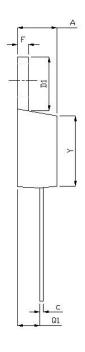


UNIT: mm



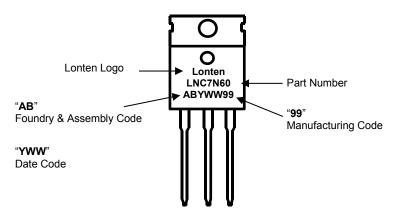
Mechanical Dimensions for TO-220





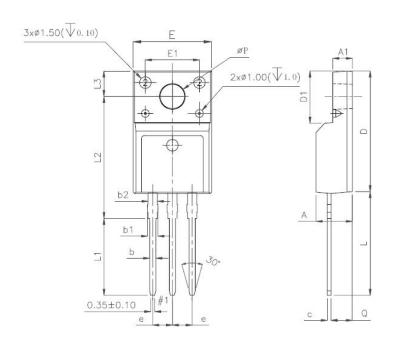
SYMBOL	MIN	NOM	MAX
Α	4		4.8
В	1.2		1.4
B1	1		1.4
b1	0.75		0.95
С	0.4		0.55
D	15		16.5
D1	5.9		6.9
E	9.9		10.7
е	2.44	2.54	2.64
F	1.1		1.4
L	12.5		14.5
L1	3	3.5	4
ФР	3.7	3.8	3.9
Q	2.5		3
Q1	2		2.9
Υ	8.02	8.12	8.22

TO-220 Part Marking Information





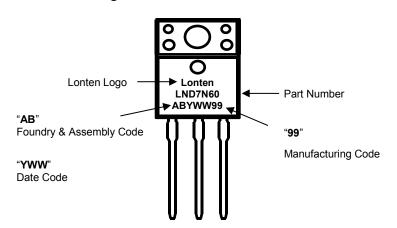
Mechanical Dimensions for TO-220F



UNIT: mm

SYMBOL	MIN	NOM	MAX
Α	4.5		4.9
A1	2.3		2.9
b	0.65		0.9
b1	1.1		1.7
b2	1.2		1.4
С	0.35		0.65
D	14.5		16.5
D1	6.1		6.9
Е	9.6		10.3
E1	6.5	7	7.5
е	2.44	2.54	2.64
L	12.5		14.3
L1	9.45		10.05
L2	15		16
L3	3.2		4.4
ФР	3		3.3
Q	2.5		2.9

TO-220F Part Marking Information





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